

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc2858hdd-2#trpbf

(Engineering Calculation)

DFN 3mm X 3mm Exp. Pad

(printed on: 2020-07-11 16:27:04)

**TOTAL MASS (g) : 0.023732**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001553	1000000	65438.0703125		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.009711	975000	409188.09375		
		Iron (Fe)	7439-89-6	0.000239	24000	10070.6367188		
		Phosphorus (P)	7723-14-0	0.000003	300	126.409667969		
		Zinc (Zn)	7440-66-6	0.000007	700	294.955871582		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.009960</b>	<b>1000000</b>	<b>419680.125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000455	1000000	19187.4140625		
		<b>External Plating Total:</b>				<b>0.000455</b>	<b>1000000</b>	<b>19187.4140625</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000225	1000000	9480.72460938		
<b>Internal Plating Total:</b>				<b>0.000225</b>	<b>1000000</b>	<b>9480.72460938</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000764	750000	32192.3261719		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000255	250000	10744.8212891		
<b>Die Attach Total:</b>				<b>0.001019</b>	<b>1000000</b>	<b>42937.1484375</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.001362	130000	57389.9882812		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.009013	860000	379776.78125		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000105	10000	4424.33837891		
		<b>Encapsulation Total:</b>				<b>0.010480</b>	<b>1000000</b>	<b>441591.09375</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000040	1000000	1685.4621582		
					<b>TOTAL MASS (g) :</b>	<b>0.023732</b>		